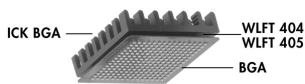


Data sheet Product ICK BGA 11 x 11 x 14



Heatsinks and active heatsinks for processors>Heatsinks for BGAs
11 x 11 x 14 mm, for IC design BGA and others

Features

way of fixation:

- therm. conductive foil
- therm. cond. adhesive

socket:

universal

suitable for processor type:

universal

width:

11 mm

height:

14 mm

plate thickness:

1.8 mm

length:

11 mm

thermal resistance:

25.5 - 6.1 K/W

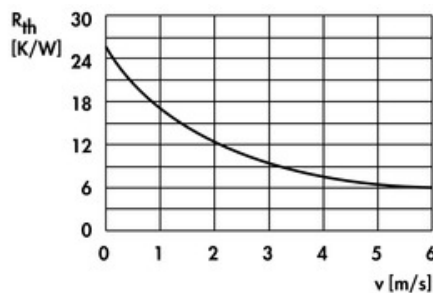
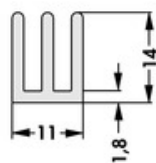
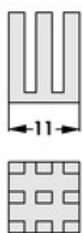
dissipation loss:

2.3 W

surface:

black anodised

Technical Drawing



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